

● **CL-2025-03 Power Dissipation**

Power dissipation data for the CL-2025-03 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: 40 x 40 mm (1600mm² in one side)

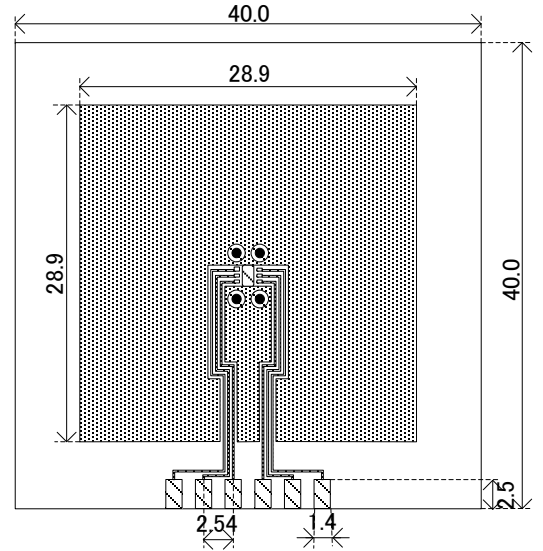
Copper (Cu) traces occupy 50% of the board area
In top and back faces Package heat-sink
is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

Copper foil thickness: Front 35um, Back 35um



Evaluation Board (Unit:mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (T_{imax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)		Thermal Resistance (°C/W)
	T _a max=85°C	T _a max=105°C	
25	800	800	125.00
85	320	320	
105	0	160	
125	0	0	

